

# MC74AC02, MC74ACT02

## Quad 2-Input NOR Gate

### High-Performance Silicon-Gate CMOS

#### Features

- Outputs Source/Sink 24 mA
- 'ACT02 Has TTL Compatible Inputs
- These are Pb-Free Devices

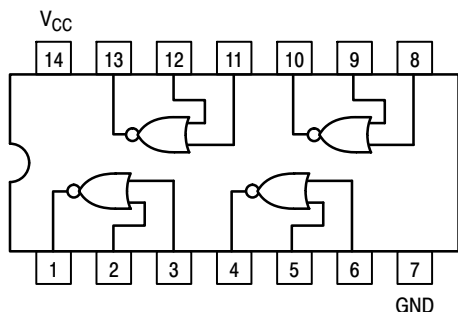


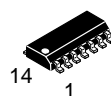
Figure 1. Pinout: 14-Lead Packages Conductors  
(Top View)



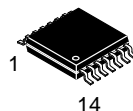
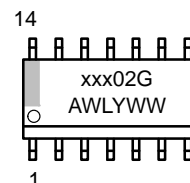
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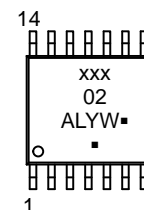
#### MARKING DIAGRAMS



SOIC-14  
D SUFFIX  
CASE 751A



TSSOP-14  
DT SUFFIX  
CASE 948G



xxx = AC or ACT  
A = Assembly Location  
WL or L = Wafer Lot  
Y = Year  
WW or W = Work Week  
G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

# MC74AC02, MC74ACT02

## MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage	− 0.5 to +7.0	V
V <sub>I</sub>	DC Input Voltage	− 0.5 ≤ V <sub>I</sub> ≤ V <sub>CC</sub> + 0.5	V
V <sub>O</sub>	DC Output Voltage (Note 1)	− 0.5 ≤ V <sub>O</sub> ≤ V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	DC Input Diode Current	± 20	mA
I <sub>OK</sub>	DC Output Diode Current	± 50	mA
I <sub>O</sub>	DC Output Sink/Source Current	± 50	mA
I <sub>CC</sub>	DC Supply Current per Output Pin	± 50	mA
I <sub>GND</sub>	DC Ground Current per Output Pin	± 50	mA
T <sub>STG</sub>	Storage Temperature Range	− 65 to + 150	°C
T <sub>L</sub>	Lead temperature, 1 mm from Case for 10 Seconds	260	°C
T <sub>J</sub>	Junction temperature under Bias	+ 150	°C
θ <sub>JA</sub>	Thermal Resistance (Note 2) SOIC TSSOP	125 170	°C/W
P <sub>D</sub>	Power Dissipation in Still Air at 85°C SOIC TSSOP	125 170	mW
MSL	Moisture Sensitivity	Level 1	
F <sub>R</sub>	Flammability Rating Oxygen Index: 30% – 35%	UL 94 V-0 @ 0.125 in	
V <sub>ESD</sub>	ESD Withstand Voltage Human Body Model (Note 3) Machine Model (Note 4) Charged Device Model (Note 5)	> 2000 > 200 > 1000	V
I <sub>Latch-Up</sub>	Latch-Up Performance Above V <sub>CC</sub> and Below GND at 85°C (Note 6)	± 100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. I<sub>O</sub> absolute maximum rating must be observed.
2. The package thermal impedance is calculated in accordance with JESD51–7.
3. Tested to EIA/JESD22–A114–A.
4. Tested to EIA/JESD22–A115–A.
5. Tested to JESD22–C101–A.
6. Tested to EIA/JESD78.

## RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Typ	Max	Unit
V <sub>CC</sub>	Supply Voltage	'AC	2.0	5.0	V
		'ACT	4.5	5.0	
V <sub>in</sub> , V <sub>out</sub>	DC Input Voltage, Output Voltage (Ref. to GND)	0	–	V <sub>CC</sub>	V
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time (Note 1) 'AC Devices except Schmitt Inputs	V <sub>CC</sub> @ 3.0 V	–	150	ns/V
		V <sub>CC</sub> @ 4.5 V	–	40	
		V <sub>CC</sub> @ 5.5 V	–	25	
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time (Note 2) 'ACT Devices except Schmitt Inputs	V <sub>CC</sub> @ 4.5 V	–	10	ns/V
		V <sub>CC</sub> @ 5.5 V	–	8.0	
T <sub>J</sub>	Junction Temperature (PDIP)	–	–	140	°C
T <sub>A</sub>	Operating Ambient Temperature Range	–40	25	85	°C
I <sub>OH</sub>	Output Current – High	–	–	–24	mA
I <sub>OL</sub>	Output Current – Low	–	–	24	mA

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

1. V<sub>in</sub> from 30% to 70% V<sub>CC</sub>; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V<sub>in</sub> from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

# MC74AC02, MC74ACT02

## DC CHARACTERISTICS

Symbol	Parameter	V <sub>CC</sub> (V)	74AC		74AC	Unit	Conditions
			T <sub>A</sub> = +25°C		T <sub>A</sub> = –40°C to +85°C		
			Typ	Guaranteed Limits			
V <sub>IH</sub>	Minimum High Level Input Voltage	3.0	1.5	2.1	2.1	V	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> – 0.1 V
		4.5	2.25	3.15	3.15		
		5.5	2.75	3.85	3.85		
V <sub>IL</sub>	Maximum Low Level Input Voltage	3.0	1.5	0.9	0.9	V	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> – 0.1 V
		4.5	2.25	1.35	1.35		
		5.5	2.75	1.65	1.65		
V <sub>OH</sub>	Minimum High Level Output Voltage	3.0	2.99	2.9	2.9	V	I <sub>OUT</sub> = –50 μA
		4.5	4.49	4.4	4.4		
		5.5	5.49	5.4	5.4		
		3.0	–	2.56	2.46	V	*V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> –12 mA I <sub>OH</sub> –24 mA –24 mA
		4.5	–	3.86	3.76		
		5.5	–	4.86	4.76		
V <sub>OL</sub>	Maximum Low Level Output Voltage	3.0	0.002	0.1	0.1	V	I <sub>OUT</sub> = 50 μA
		4.5	0.001	0.1	0.1		
		5.5	0.001	0.1	0.1		
		3.0	–	0.36	0.44	V	*V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> 12 mA I <sub>OL</sub> 24 mA 24 mA
		4.5	–	0.36	0.44		
		5.5	–	0.36	0.44		
I <sub>IN</sub>	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V <sub>I</sub> = V <sub>CC</sub> , GND
I <sub>OLD</sub>	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V <sub>OLD</sub> = 1.65 V Max
I <sub>OHD</sub>		5.5	–	–	–75	mA	V <sub>OHD</sub> = 3.85 V Min
I <sub>CC</sub>	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V <sub>IN</sub> = V <sub>CC</sub> or GND

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

\*All outputs loaded; thresholds on input associated with output under test.

†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I<sub>IN</sub> and I<sub>CC</sub> @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V<sub>CC</sub>.

## AC CHARACTERISTICS

Symbol	Parameter	V <sub>CC</sub> * (V)	74AC			74AC		Unit	Fig. No.
			T <sub>A</sub> = +25°C C <sub>L</sub> = 50 pF			T <sub>A</sub> = −40°C to +85°C C <sub>L</sub> = 50 pF			
			Min	Typ	Max	Min	Max		
t <sub>PLH</sub>	Propagation Delay	3.3 5.0	1.5 1.5	5.0 4.0	7.5 6.0	1.0 1.0	8.0 6.5	ns	3–5
t <sub>PHL</sub>	Propagation Delay	3.3 5.0	1.5 1.5	5.0 4.5	7.5 6.5	1.0 1.0	8.0 7.0	ns	3–5

\*Voltage Range 3.3 V is 3.3 V ±0.3 V.

Voltage Range 5.0 V is 5.0 V ±0.5 V.

# MC74AC02, MC74ACT02

## DC CHARACTERISTICS

Symbol	Parameter	V <sub>CC</sub> (V)	74ACT		74ACT	Unit	Conditions
			T <sub>A</sub> = +25°C		T <sub>A</sub> = –40°C to +85°C		
			Typ	Guaranteed Limits			
V <sub>IH</sub>	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> – 0.1 V
V <sub>IL</sub>	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> – 0.1 V
V <sub>OH</sub>	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I <sub>OUT</sub> = –50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> –24 mA I <sub>OH</sub> –24 mA
V <sub>OL</sub>	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I <sub>OUT</sub> = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> 24 mA I <sub>OL</sub> 24 mA
I <sub>IN</sub>	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V <sub>I</sub> = V <sub>CC</sub> , GND
ΔI <sub>CCT</sub>	Additional Max. I <sub>CC</sub> /Input	5.5	0.6	–	1.5	mA	V <sub>I</sub> = V <sub>CC</sub> – 2.1 V
I <sub>OLD</sub>	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V <sub>OLD</sub> = 1.65 V Max
I <sub>OHD</sub>		5.5	–	–	–75	mA	V <sub>OHD</sub> = 3.85 V Min
I <sub>CC</sub>	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V <sub>IN</sub> = V <sub>CC</sub> or GND

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

\*All outputs loaded; thresholds on input associated with output under test.

†Maximum test duration 2.0 ms, one output loaded at a time.

## AC CHARACTERISTICS

Symbol	Parameter	V <sub>CC</sub> * (V)	74ACT			74ACT		Unit	Fig. No.
			T <sub>A</sub> = +25°C C <sub>L</sub> = 50 pF			T <sub>A</sub> = –40°C to +85°C C <sub>L</sub> = 50 pF			
			Min	Typ	Max	Min	Max		
t <sub>PLH</sub>	Propagation Delay	5.0	1.5	–	8.5	1.0	9.0	ns	3–6
t <sub>PHL</sub>	Propagation Delay	5.0	1.5	–	9.5	1.0	10	ns	3–6

\*Voltage Range 5.0 V is 5.0 V ±0.5 V.

## CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C <sub>IN</sub>	Input Capacitance	4.5	pF	V <sub>CC</sub> = 5.0 V
C <sub>PD</sub>	Power Dissipation Capacitance	30	pF	V <sub>CC</sub> = 5.0 V

## MC74AC02, MC74ACT02

### DEVICE ORDERING INFORMATION

Device	Package	Shipping†
MC74AC02DG	SOIC–14 (Pb–Free)	55 Units / Rail
MC74AC02DR2G	SOIC–14 (Pb–Free)	2500 / Tape & Reel
MC74ACT02DG	SOIC–14 (Pb–Free)	55 Units / Rail
MC74ACT02DR2G	SOIC–14 (Pb–Free)	2500 / Tape & Reel
MC74AC02DTR2G	TSSOP–14 (Pb–Free)	2500 / Tape & Reel
MC74ACT02DTR2G	TSSOP–14 (Pb–Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

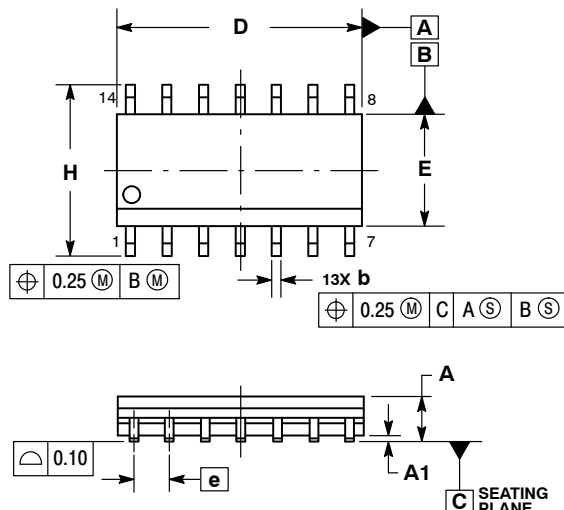
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SCALE 1:1

SOIC-14 NB  
CASE 751A-03  
ISSUE L

DATE 03 FEB 2016

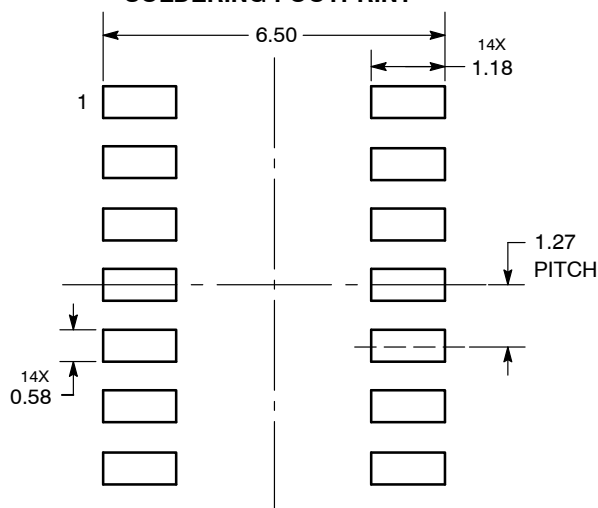


## NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
A3	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0°	7°	0°	7°

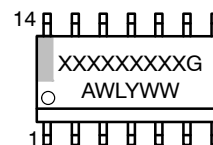
## SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## GENERIC MARKING DIAGRAM\*



XXXXXX = Specific Device Code  
A = Assembly Location  
WL = Wafer Lot  
Y = Year  
WW = Work Week  
G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

STYLES ON PAGE 2

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**SOIC-14**  
**CASE 751A-03**  
**ISSUE L**

**DATE 03 FEB 2016**

**STYLE 1:**  
PIN 1. COMMON CATHODE  
2. ANODE/CATHODE  
3. ANODE/CATHODE  
4. NO CONNECTION  
5. ANODE/CATHODE  
6. NO CONNECTION  
7. ANODE/CATHODE  
8. ANODE/CATHODE  
9. ANODE/CATHODE  
10. NO CONNECTION  
11. ANODE/CATHODE  
12. ANODE/CATHODE  
13. NO CONNECTION  
14. COMMON ANODE

**STYLE 2:**  
CANCELLED

**STYLE 3:**  
PIN 1. NO CONNECTION  
2. ANODE  
3. ANODE  
4. NO CONNECTION  
5. ANODE  
6. NO CONNECTION  
7. ANODE  
8. ANODE  
9. ANODE  
10. NO CONNECTION  
11. ANODE  
12. ANODE  
13. NO CONNECTION  
14. COMMON CATHODE

**STYLE 4:**  
PIN 1. NO CONNECTION  
2. CATHODE  
3. CATHODE  
4. NO CONNECTION  
5. CATHODE  
6. NO CONNECTION  
7. CATHODE  
8. CATHODE  
9. CATHODE  
10. NO CONNECTION  
11. CATHODE  
12. CATHODE  
13. NO CONNECTION  
14. COMMON ANODE


**STYLE 5:**  
PIN 1. COMMON CATHODE  
2. ANODE/CATHODE  
3. ANODE/CATHODE  
4. ANODE/CATHODE  
5. ANODE/CATHODE  
6. NO CONNECTION  
7. COMMON ANODE  
8. COMMON CATHODE  
9. ANODE/CATHODE  
10. ANODE/CATHODE  
11. ANODE/CATHODE  
12. ANODE/CATHODE  
13. NO CONNECTION  
14. COMMON ANODE

**STYLE 6:**  
PIN 1. CATHODE  
2. CATHODE  
3. CATHODE  
4. CATHODE  
5. CATHODE  
6. CATHODE  
7. CATHODE  
8. ANODE  
9. ANODE  
10. ANODE  
11. ANODE  
12. ANODE  
13. ANODE  
14. ANODE

**STYLE 7:**  
PIN 1. ANODE/CATHODE  
2. COMMON ANODE  
3. COMMON CATHODE  
4. ANODE/CATHODE  
5. ANODE/CATHODE  
6. ANODE/CATHODE  
7. ANODE/CATHODE  
8. ANODE/CATHODE  
9. ANODE/CATHODE  
10. ANODE/CATHODE  
11. COMMON CATHODE  
12. COMMON ANODE  
13. ANODE/CATHODE  
14. ANODE/CATHODE

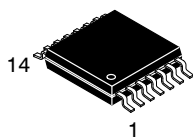
**STYLE 8:**  
PIN 1. COMMON CATHODE  
2. ANODE/CATHODE  
3. ANODE/CATHODE  
4. NO CONNECTION  
5. ANODE/CATHODE  
6. ANODE/CATHODE  
7. COMMON ANODE  
8. COMMON ANODE  
9. ANODE/CATHODE  
10. ANODE/CATHODE  
11. NO CONNECTION  
12. ANODE/CATHODE  
13. ANODE/CATHODE  
14. COMMON CATHODE

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# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

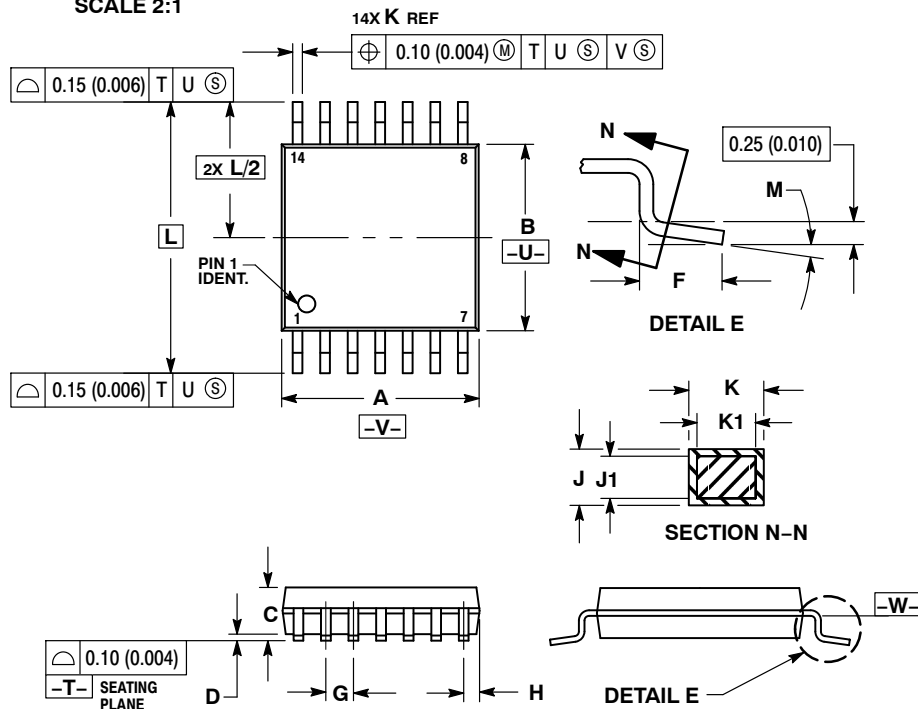
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SCALE 2:1

## TSSOP-14 WB CASE 948G ISSUE C

DATE 17 FEB 2016

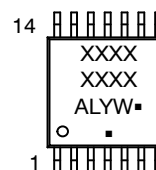


### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

### GENERIC MARKING DIAGRAM\*

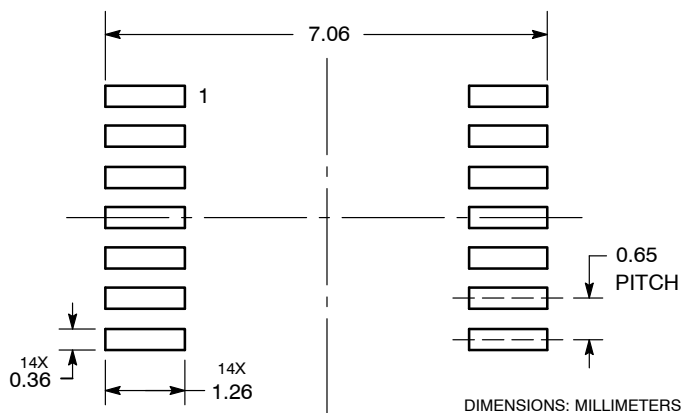


- A = Assembly Location  
L = Wafer Lot  
Y = Year  
W = Work Week  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

### SOLDERING FOOTPRINT



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